



Infineon AIROC™ Wi-Fi and Bluetooth® IoT partner module selection guide

Infinion AIROC™ Wi-Fi and Bluetooth® wireless connectivity

Delivering differentiated capabilities purpose-built for the IoT

Industry's broadest portfolio of Wi-Fi and Wi-Fi + Bluetooth® combo devices



- › Infineon has the ideal Wi-Fi solution for any application providing both single- and dual-band 802.11n/ac/ax SISO and MIMO devices.
- › Infineon provides Wi-Fi + Bluetooth® combo chipsets – integrating our world-class Wi-Fi with powerful Bluetooth®/ Bluetooth® LE to ease onboarding of cloud-connected IoT devices via a mobile app.
- › Infineon provides AIROC™ Wi-Fi connectivity processors and PSoC™ Bluetooth® MCUs with Bluetooth® LE.



- › More than 1 billion Wi-Fi devices in the field
- › High-performance RF architecture provides longer range and better interference rejection

- › Ultra low power – very low sleep, transmit, and receive current
- › Continuous improvements to battery life via a unique visibility into real-world power consumption

- › Most widely vetted Wi-Fi / Bluetooth® devices on the market, with security researchers extensively focused on Infineon
- › Deep domain knowledge and processes to help customers secure products throughout the lifecycle



Infinion wireless module partner ecosystem

Our global partner ecosystem enables development of IoT applications on time, on budget, and with minimized risk

- › **Hardware:** Avoid complicated and costly chip-down designs with a pre-built wireless module providing multiple antenna options and services.
- › **Software:** Take advantage of pre-configured connectivity software for common MPUs, operating systems, and development tools.
- › **Certifications:** Don't worry about multiple global regulatory bodies with full modular and reference-certified RF modules (CE, IC, FCC, etc.).
- › **Support:** Get to production with partner support and services including antenna and plastics design, EMC testing, and more.

muRata
INNOVATOR IN ELECTRONICS

Laird
CONNECTIVITY

AzureWave

USI

LANTRONIX
CONNECT SMART. DO MORE.

Inventek Systems
Embedding Connectivity Everywhere

Infineon IoT software solutions

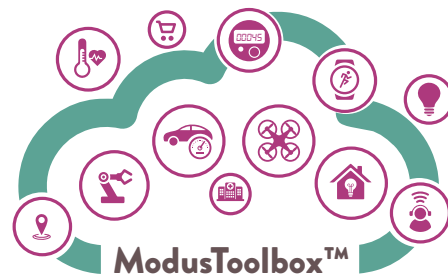


Infineon provides reliable and consistently updated software development platforms for flexible and rapid development of your connected product.

Solutions for RTOS designs

Infineon delivers compute, connectivity, and HMI capabilities in a single unified platform: The ModusToolbox™ software environment

- › ModusToolbox™ is a set of multi-platform tools and a suite of middleware libraries enabling industry-leading feature-sets like CAPSENSE™ capacitive-sensing, mesh, and system power optimization.
- › Enables an immersive development experience for Infineon MCU and wireless devices. You can use our Eclipse IDE for ModusToolbox™, or 3rd-party IDEs such as Visual Studio Code, IAR Embedded Workbench, and Keil µVision.
- › Extensive support for 3rd-party cloud ecosystems including our own cloud management solution using the ultra-low-power AIROC™ Wi-Fi connectivity processors.



Solutions for Linux/Android designs

Delivering integrated wireless products for Linux and Android designs. Infineon partners with the open-source community to provide quality and secure connectivity.

- › Enabling a broad set of Wi-Fi and Bluetooth®/Bluetooth® LE advanced feature sets for a wide variety of designs
- › Supporting the latest Linux and Android distributions along with backward-compatibility for previous versions
- › Infineon RF and regulatory tools bring your Linux- or Android-based prototype to production faster than ever



802.11ac Wi-Fi + Dual-Mode Bluetooth® combo partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Azurewave	AW-AH306	CYW43012	2.4/5 GHz, 802.11a/b/g/n with ac friendly, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	8.5 x 7	N	Y	SDIO, UART	Bluetooth® 5.0, WLCSP, ultra-low power
Azurewave	AW-AM497	CYW43012	2.4/5 GHz, 802.11a/b/g/n with ac friendly, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 12	N	Y	SDIO, UART	Bluetooth® 5.0, WLBGA, ultra-low power
Azurewave	AW-CB511NF	CYW54591	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE 5.0	Radio Only	N/A	M.2 2230	CE/FCC/IC/ NCC/Japan/ AU/NZ	Y	WLAN: PCIe Bluetooth®: UART	Certified Wi-Fi + Bluetooth® module with RSDB
Azurewave	AW-CM467	CYW4373	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE 5.1	Radio Only	N/A	12 x 12	FCC/CE	Y	WLAN: SDIO/ USB	Support SDIO or USB for Wi-Fi, UART, or USB for Bluetooth®
Azurewave	AW-CM572	CYW54591	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE 5.0	Radio Only	N/A	13 x 15	N	Y	WLAN: SDIO Bluetooth®: UART	RSDB Wi-Fi + Bluetooth® module
Azurewave	AM-342SM	CYW43012	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 12	N	Y	SDIO, UART	SiP on FR4; ultra-low power
Azurewave	AW-CM555	CYW4373	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE 5.1	Radio Only	N/A	12 x 12	N	Y	WLAN: SDIO / USB Bluetooth®: UART / USB	XTAL inside; 3-wire co-ex w/ Zigbee
Azurewave	AW-CM467- USB-I	CYW4373E	2.4/5 GHz, 802.11a/b/g/n/ac, Bluetooth®/ Bluetooth® LE 5.1	Radio Only	N/A	12 x 12	CE/FCC/IC/ NCC/Japan/ AU/NZ	Y	WLAN: SDIO / USB Bluetooth®: UART / USB	XTAL inside; I-temp
Azurewave	AW-CM467- SUR-I	CYW4373E	11a/b/g/n/ac, Bluetooth® 5.2	Radio Only	N/A	12 x 12	CE/FCC/IC/ NCC/Japan/ AU/NZ	Y	WLAN: SDIO Bluetooth®: UART	XTAL inside; I-temp
Azurewave	AW-CM590	CYW54590	11a/b/g/n/ac, Bluetooth® 5.1	Radio Only	N/A	13 x 15	CE/FCC/IC/ NCC/Japan/ AU/NZ	Y	WLAN: SDIO Bluetooth®: UART	XTAL inside; VSDB
Inventek	ISM54907- WBM-L170	CYW54907 CYW20707	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®- R4-Internal	160/ 320 MHz	11 x 11	N	N	UART, SPI, USB	Supported with SDK
Laird Connectivity	Sterling- LWB5+ (453-00045C)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Industrial temperature (-40° C to +85°C). Integrated chip antenna (Cut Tape)
Laird Connectivity	Sterling- LWB5+ (453-00045R)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Industrial temperature (-40°C to +85°C). Integrated chip antenna (Tape and Reel)

802.11ac Wi-Fi + Dual-Mode Bluetooth® combo partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Laird Connectivity	Sterling-LWB5+ (453-00046C)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Industrial temperature (-40° C to +85°C). Integrated chip antenna (Cut Tape)
Laird Connectivity	Sterling-LWB5+ (453-00046R)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Industrial temperature (-40°C to +85°C). Integrated chip antenna (Tape and Reel)
Laird Connectivity	Sterling-LWB5+ (453-00047C)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Next-gen dual band wireless IoT with 802.11ac. Industrial temperature (-40°C to +85°C), variety of different modular form factors, and industry-leading RF performance. MHF4 (Cut Tape)
Laird Connectivity	Sterling-LWB5+ (453-00047R)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 17	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART, USB	Next-gen dual band wireless IoT with 802.11ac. Industrial temperature (-40°C to +85°C), variety of different modular form factors, and industry-leading RF performance. MHF4 (Tape and Reel)
Laird Connectivity	Sterling-LWB5+ (453-00048)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	22 x 30	FCC/IC/ ETSI/Giteki/ RCM	Y	SDIO, UART	Industrial temperature (-40°C to +85°C). M.2 (E-Key) with SDIO (Wi-Fi) and UART (Bluetooth®)
Laird Connectivity	Sterling-LWB5+ (453-00049)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	22 x 30	FCC/IC/ ETSI/Giteki/ RCM	Y	USB	Industrial temperature (-40°C to +85°C). M.2 (E-Key) with USB for Wi-Fi and Bluetooth®
Lantronix	XPC270100B	CYW54907 CYW20707	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/CE	N	UART x 1, Eth (RMII), USB (Host or Device), SPI Master, SDIO, I²C, 11 GPIOs	XPICO 270 embedded IoT gw, 802.11a/b/g/n + ac Wi-Fi, ETH, Bluetooth®, dual U.FL, ind. temp., LGA, 250 pc
Lantronix	XPC270100S	CYW54907 CYW20707	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/CE	N	UART x 1, Eth (RMII), USB (Host or Device), SPI Master, SDIO, I²C, 11 GPIOs	XPICO 270 embedded IoT gw, 802.11a/b/g/n + ac Wi-Fi, ETH, Bluetooth®, dual U.FL, ind. temp., LGA, 25 pc

802.11ac Wi-Fi + Dual-Mode Bluetooth® combo partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Lantronix	XPC270300B	CYW54907 CYW20707	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®- R4-Internal	160/ 320 MHz	35 x 22	FCC/IC/CE	N	UART x 1, Eth (RMII), USB (Host or Device), SPI Master, SDIO, I²C, 11 GPIOs	XPICO 270 embedded IoT gw, 802.11a/b/g/n + ac Wi-Fi, ETH, Bluetooth®, dual U.FL, ind. temp., edge, tray, 100 PC
Lantronix	XPC270300S	CYW54907 CYW20707	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/CE	N	UART x 1, Eth (RMII), USB (Host or Device), SPI Master, SDIO, I²C, 11 GPIOs	XPICO 270 embedded IoT gw, 802.11a/b/g/n + ac Wi-Fi, ETH, Bluetooth®, dual U.FL, ind. temp., edge, single
Murata	Type 1LV (LBEE- 59B1LV-278)	CYW43012	2.4/5 GHz, 802.11a/b/g/n with ac friendly, Bluetooth®/ Bluetooth® LE	Radio only	N/A	10 x 7.2	CE/FCC/IC/ TELEC	Y	WLAN: SDIO Bluetooth®: UART	1x1 SISO 11ac + Bluetooth® solution with SDIO interface, -20°C to +70°C, Bluetooth® 5.0
Murata	Type 2AE (LBEE5P- K2AE-564)	CYW4373E	2.4/5 GHz, 802.11a/b/g/n+ ac, Bluetooth®/ Bluetooth® LE	Radio only	N/A	8.0 x 7.8	CE/FCC/IC/ TELEC	Y	WLAN: SDIO Bluetooth®: UART	1x1 SISO 11ac + Bluetooth® solution (Bluetooth® 5.0) High throughput on 11ac, -40°C to +85°C
Murata	Type 2BC (LBEE5P- K2BC-771)	CYW4373	2.4/5 GHz, 802.11a/b/g/n+ ac, Bluetooth®/ Bluetooth® LE	Radio only	N/A	8.0 x 7.8	CE/FCC/IC/ TELEC	Y	WLAN: SDIO (USB) Bluetooth®: UART (USB)	1x1 SISO 11ac + Bluetooth® solution (Bluetooth® 5.0) High throughput on 11ac, -20°C to +70°C
Murata	Type 1XA (LBEE5X- V1XA-540)	CYW54591	2.4/5 GHz, 802.11a/b/g/n + ac MIMO/ RSDB, Bluetooth®/ Bluetooth® LE	Radio only	N/A	11.4 x 8.9	FCC/IC/CE/ TELEC	Y	WLAN: PCIe Bluetooth®: UART	2x2 MIMO RSDB + Bluetooth® solution with SDIO interface, -30°C to +85°C
Murata	Type 1XZ (LBEE5X- V1XZ-892)	CYW54591	2.4/5 GHz, 802.11a/b/g/n + ac MIMO/ RSDB, Bluetooth®/ Bluetooth® LE	Radio only	N/A	11.4 x 8.9	FCC/IC/CE/ TELEC	Y	WLAN:SDIO Bluetooth®: UART	2x2 MIMO RSDB + Bluetooth® solution with SDIO interface, -30°C to +85°C
Quectel	FC80A	CYW54591	2.4/5 GHz, 802.11a/b/g/n/ac , Bluetooth®/ Bluetooth® LE	Radio Only	N/A	13 x 15 x 2.2	FCC/CE/ ROHS	Y	SDIO, UART , PCM	External antenna, supports STA & SoftAP mode, Fast Roaming & EAP
USI	WM-BA-CYW-50	PSoc™ 6 CYW43012	2.4/5 GHz, 802.11a/b/g/n + ac, Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M4 + Cortex®-M0 Internal	150/ 100 MHz	10.9 x 10.9	N	N	SDIO interface, Radio only SiP	1MB MCU FLASH+ 288KB RAM
USI	WM-BN-CYW-62	CYW43012	2.4/5 GHz, 802. 11a/b/g/n + ac, Bluetooth® 5.0	-	N/A	6.5 x 5.8	N	Y	-	-

802.11n/ac Wi-Fi + Dual-Mode Bluetooth® combo partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Azurewave	AW-NM512	CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 12	N	N	SDIO,UART	Low cost combo, 1x1 SISO, TCP keepalive, WPA-3
Azurewave	AW-CU544	P64 + CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE 5.2	Arm® Cortex®-M4F / Cortex®M0+	150MHz / 100MHz	36 x 18	FCC/IC	N	UART	Non video/audio host SoC, RTOS, CAPSENSE™, 2M Flash; OPTIGA™ Trust M, Int. Ant
Laird Connectivity	Sterling- LWB+ (453-00083R)	CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 12 x 3 (SiP module)	FCC/IC/CE/ Giteki/RCM	Y	SDIO, UART, I²S	Sterling-LWB+ Wi-Fi 4 with Bluetooth® 5.2 module, based on the Infineon AIROC™ CYW43439 chipset, is the latest member of the successful Sterling-LWB radio family. This new module series is available as a System-in-Package (SiP) and two certified module versions, supporting either an onboard chip antenna or a MHF connector for an external antenna. It is designed to meet the demands of medical and industrial IoT connectivity. Industrial temperature: Supports -40°C to +85°C industrial temperature operation.
Laird Connectivity	Sterling- LWB+ (453-00084R)	CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	21 x 15 x 4 (PCB module)	FCC/IC/CE/ Giteki/RCM	Y	SDIO, UART, I²S	Sterling-LWB+ Wi-Fi 4 with Bluetooth® 5.2 module, based on the Infineon AIROC™ CYW43439 chipset, is the latest member of the successful Sterling-LWB radio family. This new module series is available as a System-in-Package (SiP) and two certified module versions, supporting either an onboard chip antenna or a MHF connector for an external antenna. It is designed to meet the demands of medical and industrial IoT connectivity. Industrial temperature: Supports -40°C to +85°C industrial temperature operation.
Laird Connectivity	Sterling- LWB+ (453-00085R)	CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	21 x 15 x 4 (PCB module with chip antenna)	FCC/IC/CE/ Giteki/RCM	Y	SDIO, UART, USB	Sterling-LWB+ Wi-Fi 4 with Bluetooth® 5.2 module, based on the Infineon AIROC™ CYW43439 chipset, is the latest member of the successful Sterling-LWB radio family. This new module series is available as a System-in-Package (SiP) and two certified module versions, supporting either an onboard chip antenna or a MHF connector for an external antenna. It is designed to meet the demands of medical and industrial IoT connectivity. Industrial temperature: Supports -40°C to +85°C industrial temperature operation.

802.11n/ac Wi-Fi partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Lantronix	XPC240100B-02	CYW43907	2.4/5 GHz, 802.11n	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/ CE/TELEC/ SRRC	N	UART x 1, Eth (RMII), USB (Host or De- vice), SPI, SDIO, I²C, 11 GPIOs	XPICO 240 embedded IoT gw, 802.11a/b/g/n + ac, ETH, dual U.FL, ind. temp., LGA, 250
Lantronix	XPC240200B-02	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/ CE/TELEC/ SRRC	N	UART x 1, Eth (RMII), USB (Host or Device), SPI (Master and Slave), SDIO, I²C, 11 GPIOs	XPICO 240 embedded IoT gw, 802.11a/b/g/n, ETH, 0n-module ant, ind. temp., LGA, 250
Lantronix	XPC240300B-02	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/ CE/TELEC/ SRRC	N	UART x 1, Eth (RMII), USB (Host or De- vice), SPI, SDIO, I²C, 11 GPIOs	XPICO 240 embedded IoT gw, 802.11a/b/g/n, ETH, dual U.FL, ind. temp., edge conn, 100 pc
Lantronix	XPC240400B-02	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	25 x 17	FCC/IC/ CE/TELEC/ SRRC	N	UART x 1, Eth (RMII), USB (Host or De- vice), SPI, SDIO, I²C, 11 GPIOs	XPICO 240 embedded IoT gw, 802.11a/b/g/n, ETH, 0n-module ant, ind. temp., edge conn, 100 pc
Murata	Type 1GC (LB- WA1UZ1GC-958)	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	10 x 10	CE/FCC/IC	N	UART, SPI, I²C, I²S, PWM, GPIO, USB, Ethernet	High performance CPU. Gateway for WLAN and Ethernet. Audio streaming. Modular Cert. RAM 2 MB, -20°C to +70°C, Arrow Quicksilver EVK support
Murata	Type 1PS (LB- WA1UZ1PS-241)	CYW54907	2.4/5 GHz, 802.11a/b/g/n + ac	Arm® Cortex®- R4-Internal	160/ 320 MHz	10 x 10	CE/FCC/IC	N	UART, SPI, I²C, I²S, PWM, GPIO, USB, Ethernet	High performance CPU. Gateway for WLAN and Ethernet. Audio streaming. Modular Cert. RAM 2 MB, -20°C to +70°C, Pin compatible with type 1GC (adds 802.11ac)
Murata imp	Type 1GC Imp005 (LB- WA1UZ1GC-901)	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	10 x 10	CE/FCC/IC	N	UART, SPI, I²C, PWM, GPIO, USB, Ethernet	Electric Imp, High performance CPU. Gateway for WLAN and Ethernet. Audio streaming. Modular Cert. RAM 2 MB, -20°C to +70°C
Murata	Type 1YN (LBEE5KL1YN)	CYW43439	802.11b/g/n + Bluetooth® 5.2 BR/EDR/LE	Radio Only	N/A	6.95 x 5.15 x 1.1	FCC/IC		WLAN-SDIOv2.0, UART & PCM	Small form factor, high-performance module with up to 65 Mbps PHY data rate on Wi-Fi and 3 Mbps PHY data rate on Bluetooth®
Quectel	FC909A	CYW43439	2.4 GHz, 802.11b/g/n, Bluetooth®/ Bluetooth® LE	Radio Only	N/A	12 x 12 x 1.95	FCC/CE/ ROHS	Y	SDIO, UART, PCM	External antenna, supports STA & SoftAP mode, Fast Roaming & EA
USI	WM-AN-BM-23	CYW43907	2.4/5 GHz, 802.11a/b/g/n	Arm® Cortex®- R4-Internal	160/ 320 MHz	10 x 10	CE/FCC/IC	N	QSPI, PWM, USB, SDIO, UART, I²C, I²S, MII, RMII	2 MB RAM
USI	WM-BN-BM-26_ REF1	CYW43439	2.4 GHz, 11b/g/n/ Bluetooth® 5.2	Radio Only	N/A	15 x 9.5	N	Y	SDIO (WPA3)	-

Bluetooth® & Bluetooth®LE (Dual-Mode) partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Alinket	ALX41X	CYW20736	Bluetooth® LE	Arm® Cortex®-M3-Internal	24 MHz	19 x 13.5	FCC/CE	N	UART, SPI ADC, GPIO	PCB antenna, 1 MB Flash, Bluetooth® LE MIDI support, master mode (up to 8 slaves) & bridge mode.
Alinket	ALX420	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M3-Internal	96 MHz	8 x 8	N	N	HCI UART, PUART SPI, I²S, I²C, ADC	Custom antenna designs supported, supports master/slave mode, A2DP SRC & SNK & iAP2, MFi (HomeKit).
Alinket	ALX420A	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M3-Internal	96 MHz	16 x 10	FCC/CE	N	HCI UART, PUART SPI, I²S, I²C, ADC	Onboard antenna, 1 MB Flash, supports Master/Slave mode, A2DP SRC & SNK & iAP2, MFi (HomeKit).
Alinket	ALX421A	CYW20707	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M4-STM32F411	100 MHz	19 x 12	FCC/CE	N	UART, SPI, USB, SDIO, I²S, I²C	Onboard antenna, 1 MB Flash, supports master/Slave mode, A2DP SRC & SNK & iAP2, MFi (HomeKit).
Alinket	ALX422A	CYW20707	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M4-STM32F412	100 MHz	21 x 12	FCC/CE	N	UART, SPI, USB, SDIO, I²S, I²C	Bluetooth® 4.2, onboard antenna, 1 MB Flash, support both slave & master mode, A2DP SRC & SNK, HFP & iAP2, MFi (HomeKit).
Alinket	ALXG30	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M4-STM32F411	100 MHz	80 x 55	FCC/CE	Y	RS485	Onboard or external antenna (with U.FL connector), 1 MB Flash, supports Bluetooth® slave mode, SPP, MFi, RS485 to Bluetooth®, RS-485 to 2G.
Azurwave	AW-BT315W	CYW20721	Bluetooth® 5.1	Arm® Cortex® - M4	96 MHz	4 x 4	N	Y	UART	Small form-factor Bluetooth® SiP module.
Inventek	ISM20706A2S	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®-M3-Internal	96 MHz	6.0 x 8.6	N	N	SPI, I²C, JTAG	Embedded antenna Bluetooth®4.2+HS SiP module.
Inventek	ISM20732S	CYW20732	Bluetooth® LE	Arm® Cortex®-M3-Internal	24 MHz	6.5 x 6.5	FCC/IC/CE	N	SPI, I²C, JTAG	Lowest cost Bluetooth® LE SiP module solution.
Inventek	ISM20736S	CYW20736	Bluetooth® LE	Arm® Cortex®-M3-Internal	24 MHz	6.5 x 6.5	FCC/IC/CE	N	SPI, I²C, JTAG	Wireless charging, simultaneous central and peripheral operation.
Iton	BB2706-30	CYW20707	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	15 x 12	N	Y	SPI, UART, I²C	Bluetooth® 4.2, supported profile: HFP with WBS, HID, SPP, GATT, AVRCP, HOGP, A2DP, HID, etc; supports SiG Bluetooth® LE mesh, customized flow control for portable printers.

Bluetooth® & Bluetooth®LE (Dual-Mode) partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Laird Connectivity	Bluetooth®- 850-SA	CYW20704	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	8.5 x 13	FCC/IC/CE/ RCM/Giteki/ Korea	Y	USB, HCI, I²S, PCM, GPIO	The Bluetooth® 85x series of USB HCI modules and adapters that leverages the CYW20704 A2 chipset to provide exceptionally low power consumption with outstanding range for OEMs needing both classic Bluetooth® and Bluetooth® LE support. The Bluetooth® v5 core specification shortens your development time and provides enhanced throughput, security and privacy. The Bluetooth® 850 modules are ideal when designers need both performance and minimum size. For maximum flexibility in integration, they support a host USB interface, I²S and PCM audio interfaces, GPIO, and GCI coexistence (2-Wire). The modules provide excellent RF performance and identical footprint options for integrated antenna or an external antenna via a trace pin.
Laird Connectivity	Bluetooth®- 850-ST	CYW20704	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	8.5 x 13	FCC/IC/CE/ RCM/Giteki/ Korea	Y	USB, HCI, I²S, PCM, GPIO	The Bluetooth® 85x series of USB HCI modules and adapters that leverages the CYW20704 A2 chipset to provide exceptionally low power consumption with outstanding range for OEMs needing both classic Bluetooth® and Bluetooth® LE support. The Bluetooth® v5 core specification shortens your development time and provides enhanced throughput, security and privacy. The Bluetooth® 850 modules are ideal when designers need both performance and minimum size. For maximum flexibility in integration, they support a host USB interface, I²S and PCM audio interfaces, GPIO, and GCI coexistence (2-Wire). The modules provide excellent RF performance and identical footprint options for integrated antenna or an external antenna via a trace pin.

Bluetooth® & Bluetooth®LE (Dual-Mode) partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Laird Connectivity	Bluetooth® 851	CYW20704	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	17.4 x 46.75	FCC/IC/CE/ RCM/Giteki	Y	USB, HCI, I²S, PCM, GPIO	The Bluetooth® 851 is a packaged USB adapter that leverages the CYW20704 A2 chipset to provide exceptionally low power consumption with outstanding range for OEMs needing both classic Bluetooth® and Bluetooth® LE support. The Bluetooth® v5 core specification shortens your development time and provides enhanced throughput, security and privacy.
Laird Connectivity	Bluetooth® -860-SA	CYW20704	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	8.5 x 12.85	FCC/IC/CE/ RCM/Giteki	Y	UART, HCI, I²S, PCM, GPIO	The Bluetooth® 86x series of UART HCI modules that leverages the CYW20704 A2 chipset to provide exceptionally low power consumption with outstanding range for OEMs needing both Classic Bluetooth® and Bluetooth® LE support. The Bluetooth® v5 core specification shortens your development time and provides enhanced throughput, security and privacy. The Bluetooth® 860 modules are ideal when designers need both performance and minimum size. For maximum flexibility in integration, they support a host UART interface, I²S and PCM audio interfaces, GPIO, and GCI coexistence (2-Wire). The modules provide excellent RF performance and identical footprint options for integrated antenna or an external antenna via a trace pin.
Laird Connectivity	Bluetooth®-860-ST	CYW20704	Bluetooth®/ Bluetooth® LE	Radio Only	N/A	8.5 x 12.85	FCC/IC/CE/ RCM/Giteki	Y	UART, HCI, I²S, PCM, GPIO	The Bluetooth® 86x series of UART HCI modules that leverages the CYW20704 A2 chipset to provide exceptionally low power consumption with outstanding range for OEMs needing both Classic Bluetooth® and Bluetooth® LE support. The Bluetooth® v5 core specification shortens your development time and provides enhanced throughput, security and privacy. The Bluetooth® 860 modules are ideal when designers need both performance and minimum size. For maximum flexibility in integration, they support a host UART interface, I²S and PCM audio interfaces, GPIO, and GCI coexistence (2-Wire). The modules provide excellent RF performance and identical footprint options for integrated antenna or an external antenna via a trace pin.

Bluetooth® & Bluetooth®LE (Dual-Mode) partner module portfolio

Partner	PN	Wi-Fi/ Bluetooth® PN	Wi-Fi/Bluetooth® Support	MCU	CPU (MHz)	Area (mm)	Regulatory	Linux	Interfaces	Highlights
Murata	Type 1GR (LBCA1ZZ1GR-084)	CYW20736	Bluetooth® LE	Arm® Cortex®- M3-Internal	24 MHz	9.0 x 7.0	CE/FCC/IC	N	UART, SPI	Bluetooth® 4.1, includes antenna
Murata	Type1WA	CYW20721	Bluetooth®/ Bluetooth® LE	Arm® Cortex®- M4-Internal	N/A	5.9 x 5.1	FCC/IC/CE	Y	UART, SPI	Bluetooth® 5.1, Performance Audio
Pairlink	Dragon-B	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®- M3-Internal	96 MHz	11 x 16.8	BQB/MIC/ FCC/IC/CE/ ROHS	N	UART, 4*PWM, MFi, IIS	Chip antenna, 1 MB Flash, supports connected mesh, SIG mesh
Pairlink	Dragon-C	CYW20706	Bluetooth®/ Bluetooth® LE	Arm® Cortex®- M3-Internal	96 MHz	11 x 16.8	BQB/MIC/ FCC/IC/CE/ ROHS	N	UART, 4*PWM, MFi, IIS	IPEX connector, 1 MB Flash, supports connected mesh, SIG mesh
Pairlink	Mouselet-B	CYW20736	Bluetooth® LE	Arm® Cortex®- M3-Internal	24 MHz	14 x 18	BQB/MIC	N	UART, 4*PWM	Chip antenna, 512 KB Flash, supports connected mesh
Pairlink	Mouselet-C	CYW20736	Bluetooth® LE	Arm® Cortex®- M3-Internal	24 MHz	14 x 18	BQB/MIC	N	UART, 4*PWM	IPEX connector, 512 KB Flash, supports connected mesh

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